

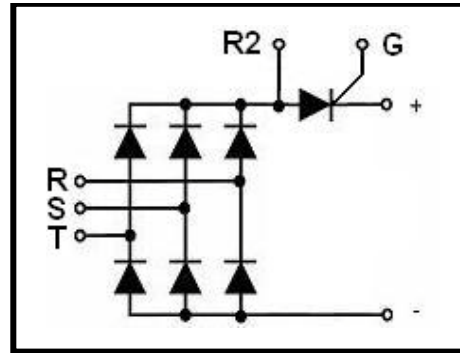
## Features

- Isolated Module Package
- Isolation voltage 3000 V
- Three Phase Bridge and a Thyristor



## Applications

- Current Stabilized Power Supply
- Switching Power Supply
- Inverter For AC or DC Motor Control



## ■ Diode

### ABSOLUTE MAXIMUM RATINGS

T<sub>C</sub>=25°C unless otherwise specified

Symbol	Parameter	Test Conditions	Max.	Unit
V <sub>RRM</sub> / V <sub>DRM</sub>	Repetitive Reverse Voltage		1600	V
I <sub>D(AV)</sub>	Average Forward Current	T <sub>C</sub> =90°C, module	200	A
I <sub>FSM</sub>	Non-Repetitive Surge Forward Current	T <sub>J</sub> =45°C, t=10ms, 50Hz, Sine	1850	A
		T <sub>J</sub> =45°C, t=8.3ms, 60Hz, Sine	2000	A
I <sup>2</sup> t	I <sup>2</sup> t (For Fusing)	T <sub>J</sub> =45°C, t=10ms, 50Hz, Sine	17100	A <sup>2</sup> s
		T <sub>J</sub> =45°C, t=8.3ms, 60Hz, Sine	20000	A <sup>2</sup> s
T <sub>J</sub>	Junction Temperature		-40~150	°C
T <sub>STG</sub>	Storage Temperature Range		-40~125	°C
V <sub>ISOL</sub>	Insulation Test Voltage	50Hz, all terminals shorted, t=5s, I <sub>ISOL</sub> ≤1mA ;	3500	V
Weight			332	g

### ELECTRICAL AND THERMAL CHARACTERISTICS

T<sub>C</sub>=25°C unless otherwise specified

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I <sub>RM</sub>	Reverse Leakage Current	V <sub>R</sub> =1600V	--	--	500	μA
		V <sub>R</sub> =1600V, T <sub>J</sub> =125°C	--	--	4	mA
V <sub>F</sub>	Forward Voltage	I <sub>F</sub> =200A	--	--	1.4	V
		I <sub>F</sub> =200A, T <sub>J</sub> =125°C	--	1.2	--	V
R <sub>θJC</sub>	Thermal Resistance	per diode	--	--	0.72	°C/W
	Junction-to-Case	per module	--	--	0.12	°C/W
R <sub>θCS</sub>	Thermal Resistance	per diode	--	--	0.36	°C/W
	Case -to-Sink	per module	--	--	0.06	°C/W

## ■ Thyristor

### ABSOLUTE MAXIMUM RATINGS

$T_C=25^\circ\text{C}$  unless otherwise specified

Symbol	Test Condition	Value	Unit
$V_{RRM}$		1600	V
$I_{T(AV)}$	$T_C=90^\circ\text{C}$ , 180° conduction, half sine wave;	200	A
$I_{TSM}$	$T_J=45^\circ\text{C}$ , $t=10\text{ms}$ (50Hz), sine, $V_R=V_{RRM}$ ;	1850	A
	$T_J=45^\circ\text{C}$ , $t=8.3\text{ms}$ (60Hz), sine, $V_R=V_{RRM}$ ;	2000	
$I^2t$	$T_J=45^\circ\text{C}$ , $t=10\text{ms}$ (50Hz), sine, $V_R=V_{RRM}$ ;	17100	$\text{A}^2\text{s}$
	$T_J=45^\circ\text{C}$ , $t=8.3\text{ms}$ (60Hz), sine, $V_R=V_{RRM}$ ;	20000	
dv/dt	$T_J=125^\circ\text{C}$ , linear to $0.67V_{DRM}$	1000	V/us
di/dt	$T_J=125^\circ\text{C}$ , $I_{TM}=500\text{A}$ , from $0.67V_{DRM}$	200	A/us
$V_{ISOL}$	50Hz, all terminals shorted, $t=5\text{s}$ , $I_{ISOL}\leq 1\text{mA}$ ;	3500	V~
$T_J$	Max. junction operating temperature range	-40~125	$^\circ\text{C}$
$T_{STG}$	Max. storage temperature range	-40~125	$^\circ\text{C}$
$M_d$	Mounting torque(M6)	3 to 5	N·m
	Terminal connection torque(M6)	3 to 5	N·m
	Terminal connection torque(M4)	1 to 2	N·m

### ELECTRICAL AND THERMAL CHARACTERISTICS

$T_C=25^\circ\text{C}$  unless otherwise specified

Symbol	Test Condition	Min.	Typ.	Max.	Unit
$I_{DRM}/I_{RRM}$	$V_D=V_R=1600\text{V}$ ;			500	$\mu\text{A}$
$I_{DRM}/I_{RRM}$	$T_J=125^\circ\text{C}$ , $V_D=V_R=1600\text{V}$ ;			100	mA
$V_{TM}$	$I_{TM}=200\text{A}$ , $t_d=10\text{ms}$ , half sine;			1.4	V
$V_{GT}$	$V_A=6\text{V}$ , $R_A=1\Omega$ , $T_J=-40^\circ\text{C}$ ;			4	V
	$V_A=6\text{V}$ , $R_A=1\Omega$ ;			3.2	
	$V_A=6\text{V}$ , $R_A=1\Omega$ , $T_J=125^\circ\text{C}$ ;			1.7	
$I_{GT}$	$V_A=6\text{V}$ , $R_A=1\Omega$ , $T_J=-40^\circ\text{C}$ ;			270	mA
	$V_A=6\text{V}$ , $R_A=1\Omega$ ;			140	
	$V_A=6\text{V}$ , $R_A=1\Omega$ , $T_J=125^\circ\text{C}$ ;			80	
$P_{GM}$	$t_p\leq 5\text{ms}$ , $T_J=125^\circ\text{C}$ ;			12	W
$P_{GM(AV)}$	$f=50\text{Hz}$ , $T_J=125^\circ\text{C}$ ;			3	W
$R_{thjc}$	Thermal Resistance, Junction-to-Case			0.15	K/W
$R_{THCS}$	Thermal Resistance, Case -to-Sink			0.07	K/W

Characteristic curves

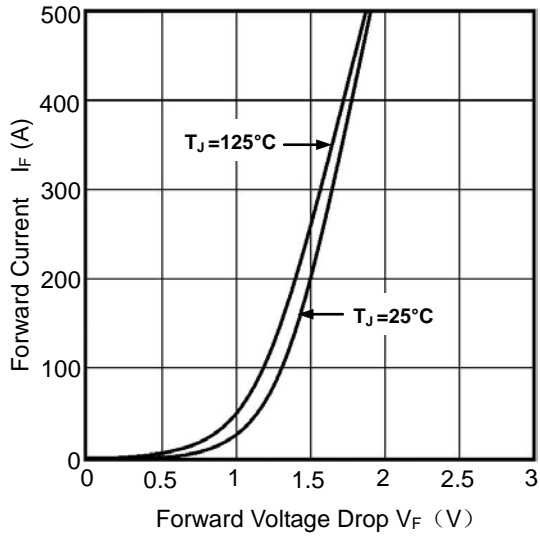


Figure 1. Diode Forward Voltage Drop vs Forward Current

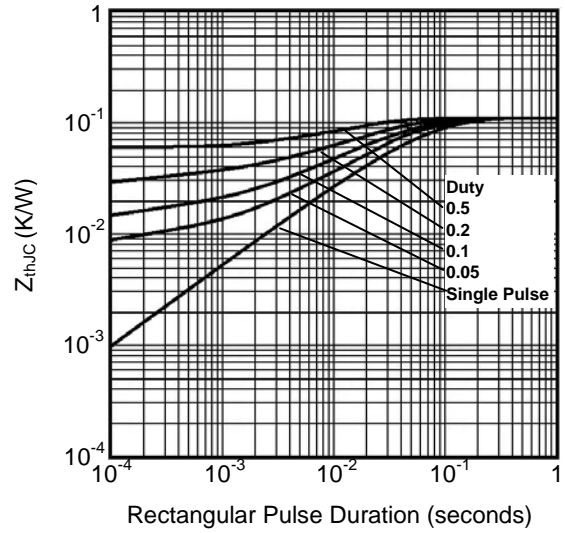


Figure 2. Diode Thermal Impedance  $Z_{thJC}$

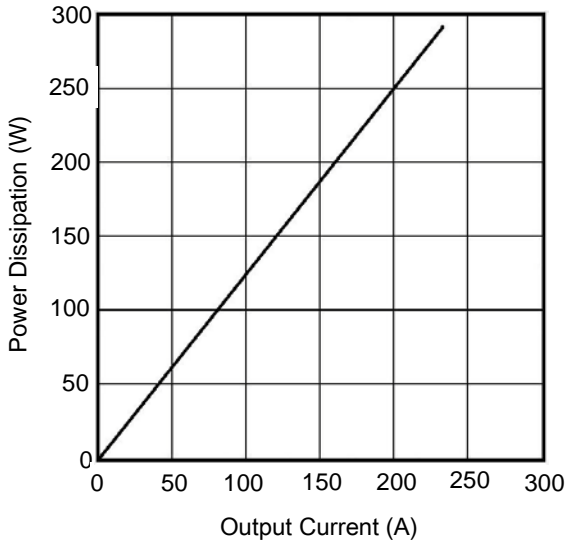


Figure 3. SCR Output Current vs Power Dissipation

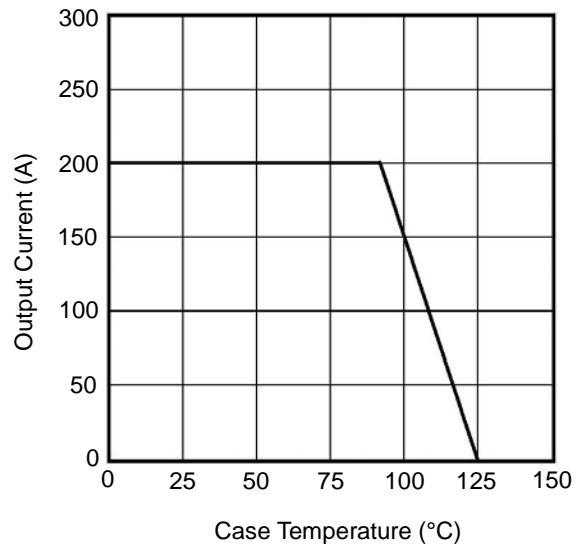


Figure 4. SCR Output Current vs Case Temperature

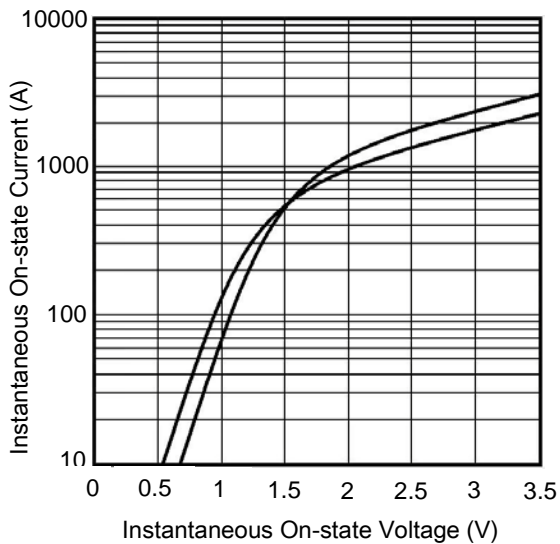


Figure 5. SCR On State Voltage Drop

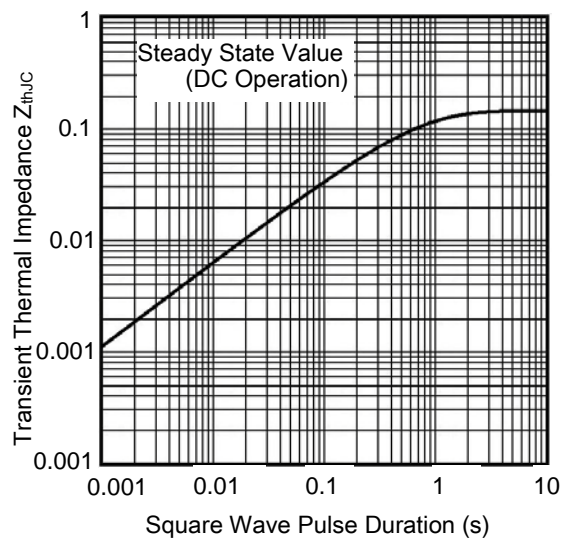


Figure 6. SCR Thermal Impedance  $Z_{thJC}$

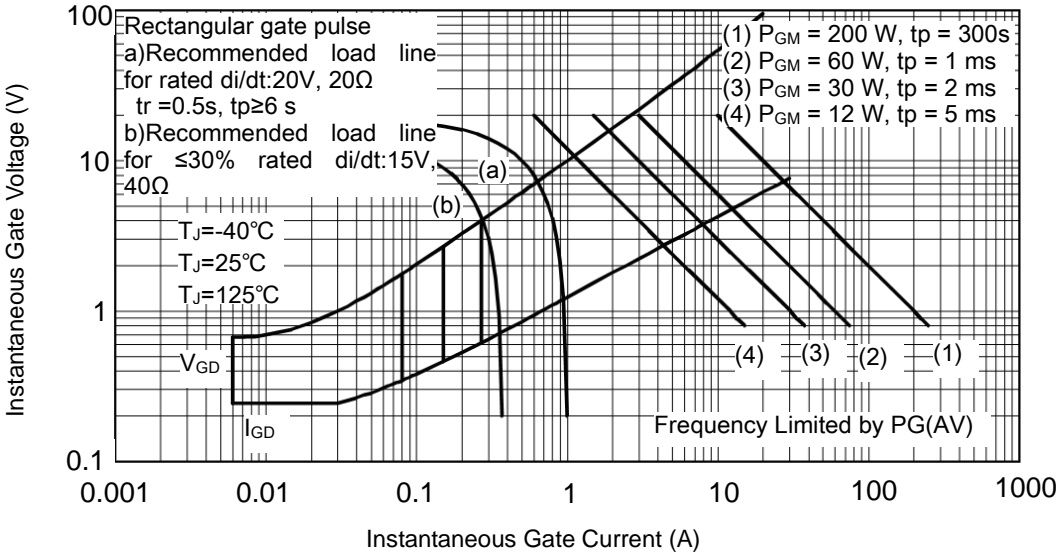


Figure 7. Gate Characteristics

Package Outline (Dimensions in mm)

